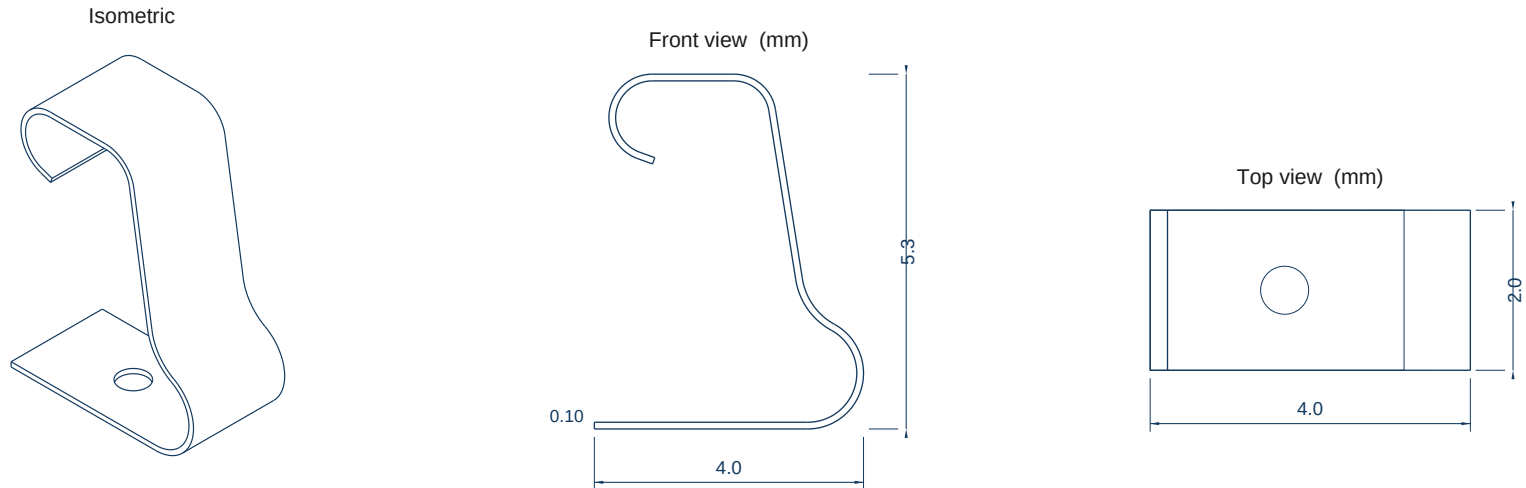




Type C-11 BC11-20040053

SMD EMI Spring Contact | Beryllium Copper | Units: mm



MECHANICAL

VALUE

Thickness	0.10 mm
Width	2.0 mm +/- 0.2
Length	4.0 mm +/- 0.2
Height	5.3 mm +/- 0.2
Form	base plate, S-bend riser, top arm, curled end hook
S-bend	R0.778 CL, 151 deg then R0.991 CL, 52 deg
Top bend	R0.577 CL, 81 deg
End hook	R0.597 CL, 160 deg
Riser	2.54 mm
Base hole	dia 0.60 mm at 1.68 from the base end
Developed length	12.60 mm
Material / plating	BeCu, Gold-plated (G)
Volume / mass	2.492 mm ³ 20.8 mg (BeCu)

PRODUCT DATA

VALUE

Mfr P/N	BC11-20040053G-SY (Au)
Brand	Seyunda
Description	SMD EMI Contact 4.0x2.0x5.3mm Au
Packaging	Tape & Reel (TR)
Category	Connectors, Interconnects
Sub-category	Contacts, Spring Loaded (Pogo Pins), and Pressure
Lifecycle / origin	Active / Taiwan, Republic of China
RoHS / REACH	RoHS3 Compliant / REACH Unaffected
ECCN / ESD	EAR99 / Static sensitive: Yes
Datasheet	seyunda.com/datasheet/Seyunda-SMD-Spring-Contacts-Datasheet.pdf
Product page	seyunda.com/type-c-11.html
File format	STEP AP214